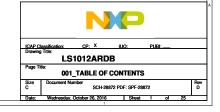
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# LS1012A RDB REV - D

All information is subject to change without notice. No warranty, expressed or applied, is made as to the accuracy of the information contained herein. This schematic is provided for reference purposes only. Contact your NXP representative to obtain the latest information on this product.

Rev	Date	Changes	٦
X1	10/09/2015	First Release	┪
X2	18/09/2015	Implemented internal review comments	٦
ХЗ	19/11/2015	Implemented changes required for Layout.	٦
Α	23/11/2015	A85 Release. Implemented Power_OK changes.	٦
AX1	28/12/2015	A70 Release: Architecture changes for UART & JTAG MUX.	٦
AX2	15/1/2016	A70 Release: UART transceiver and bringup erratas.	٦
В	28/1/2016	A85 Release.	٦
BX1	28/4/2016	Implemented bringup errata. Refre Errata for more details.	٦
С	03/05/2016	A85 Release.	٦
CX1	03/06/2016	Added on board oscillator(25MHz) with Clock buffer to provide reference clock for LS1012 SOC and SGMII PHY. Errata in power mux 3.3V.	
D	26/10/2016	A085 release.	٦



# LS1012RDB Block Diagram E LS1012 SGMII(1G) TXCLK SD Connector SVDD=0.9V,X1VDD,AVDD\_SR\_PLL=1. From 12C IO EXPANDER (INTERRUPT& GPIO) OR Bue both USB\_HVDD=3V3, SV,SD\_VDD=0.9V USB2.08USB3.0 UART1 25 MHz Cryst al JTAG . SW[1:2] PORCEG & RESET RESET 🧓 LED's (PG & RESET) 12V DC INPUT On Board Power Supply \_12V From PoE Isolated Regulator 3.6V/5V from Battery/USB



# **PCB STACKUP**

# NOTE:

Stackup with low loss material TU-872LK is shown below but any stackup which meets impedance requirements can be used.

1.Materials: TU-872LK

2.trace/space (min): 3/3 mils

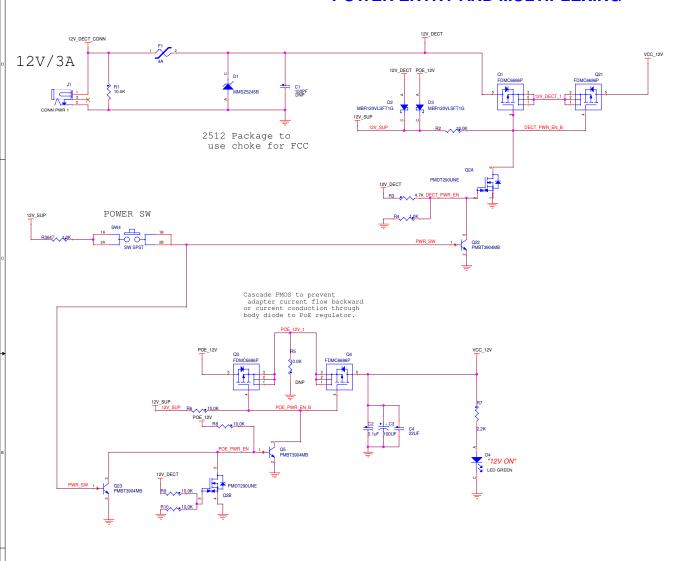
finish copper (Max): 1.1mils

3.HDI design:(yes or no): no

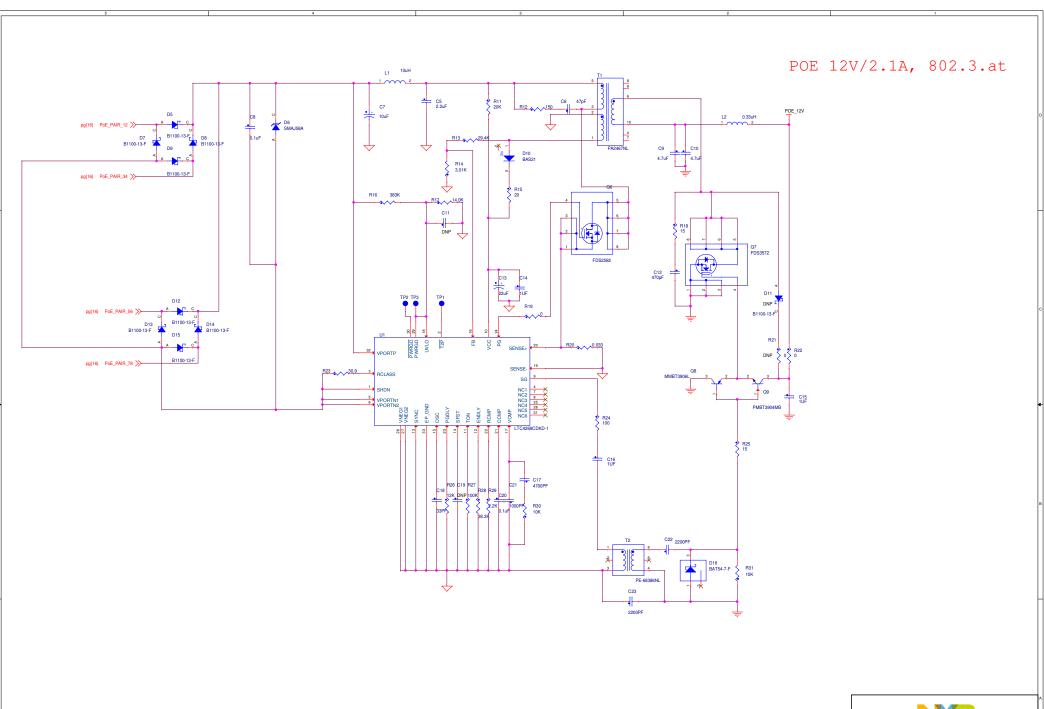
Propose PCB Stack Up								Impeda	ance					
Layer	Туре	Thickness (mil)		Single end	Ω	+/- 1/0	REF	Theory value	Differential	Ω	+/- 10/0	REF	Theory value	
	Top side so	older mask	0.70	mils		a.		13					- k	
L1	TOP	copper+plating	1.10	mils	w: 6.5 mils	50	10	2	47.96	W: 6/6/6 mils W: 5/8/5 mils	90 100	10 10	2 2	87.72 99.36
t 3		dielectric layer	3.50	mils										
L2		copper	1.30	mils										
		dielectric layer	6.10	mils										
L3		copper	0.70	mils	w: 6.5 mils	50	10	2 5	48.52	<b>W:</b> 5/8/5 mils	100	10	2 5	98.39
		dielectric layer	37.00	mils										
L4		copper	0.70	mils	w: 6.5 mils	50	10	2 5	48.52	<b>W:</b> 5/8/5 mils	100	10	2 5	98.39
		dielectric layer	6.10	mils							Î			
L5		copper	1.30	mils										
		dielectric layer	3.50	mils							Į			
L6	Bottom	copper+plating	1.10	mils	w: 6.5 mils	50	10	2	47.96	W: 6/6/6 mils W: 5/8/5 mils	90 100	10 10	2 2	87.72 99.36
	Top side so	older mask	0.70	mils										
	TO	TAI	63.80	mils		Ĭ.								
	10	IAL	1.62	mm					0.00	·				



# **POWER ENTRY AND MULTIPLEXING**

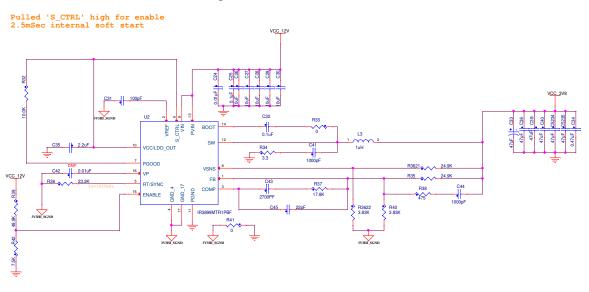




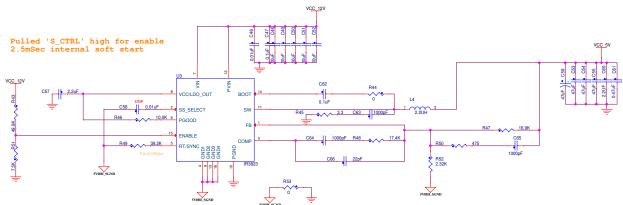




#### POWER 3.8V @ 9A

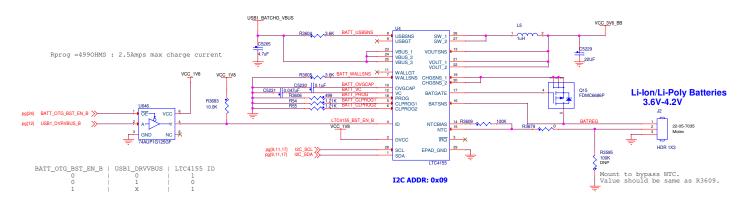


# POWER 5V @ 3A

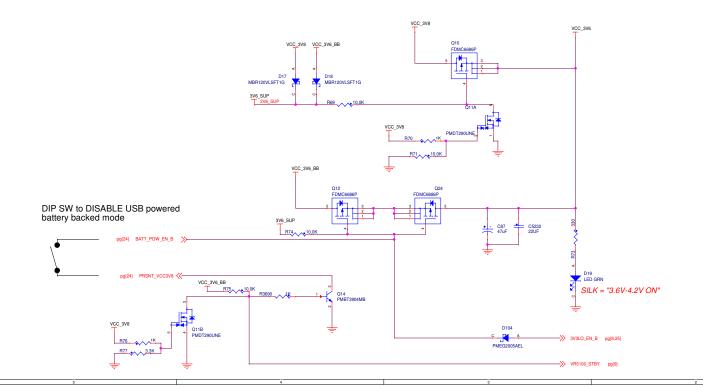


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# **Li-ion Battery Charger & Power Manager**

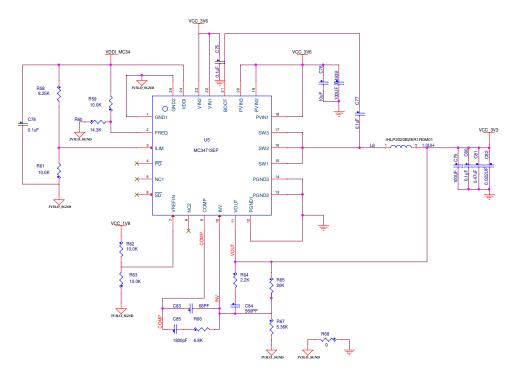


# 3.6V PFET MUX (External/PoE & USB/Battery)

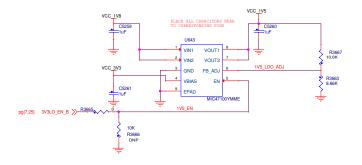




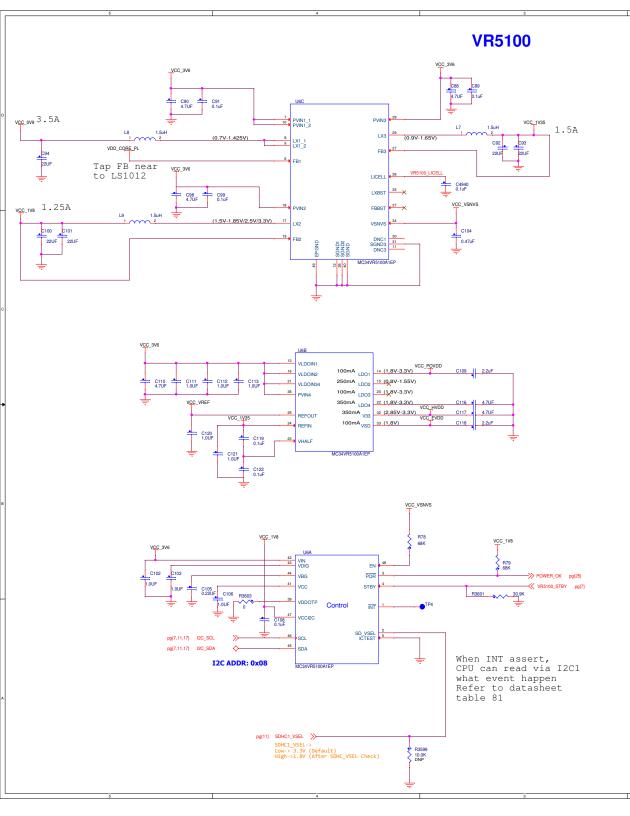
# **POWER 3.3V**

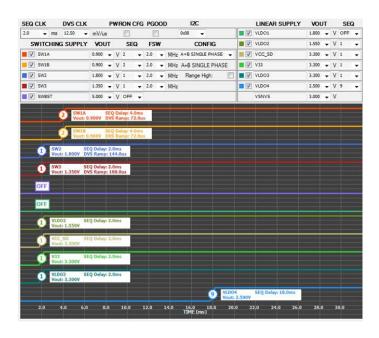


#### Mini PEX (1.5V)



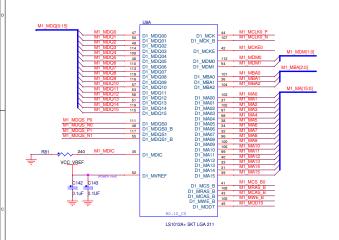
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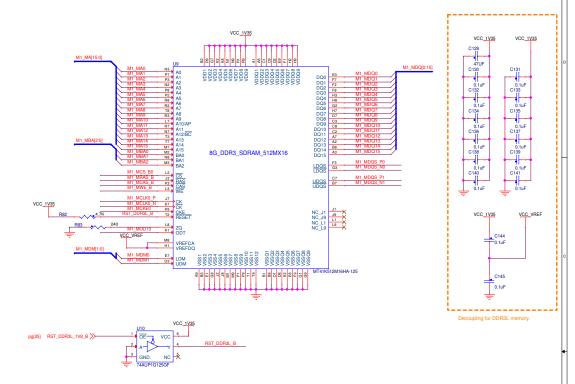




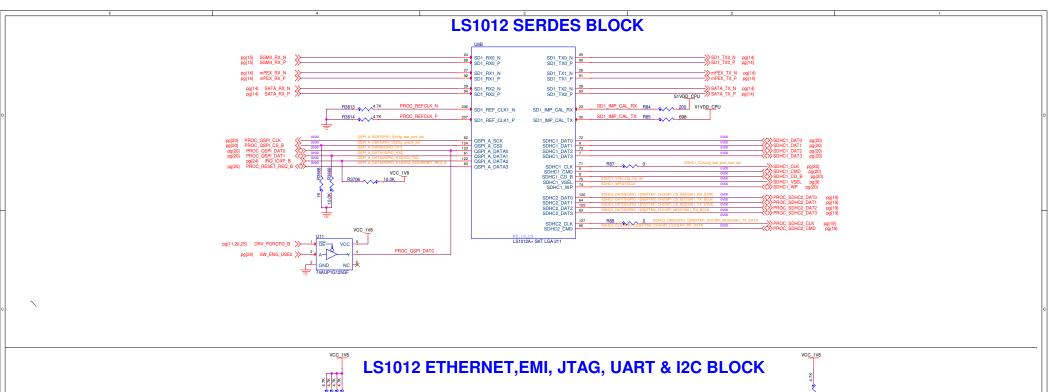


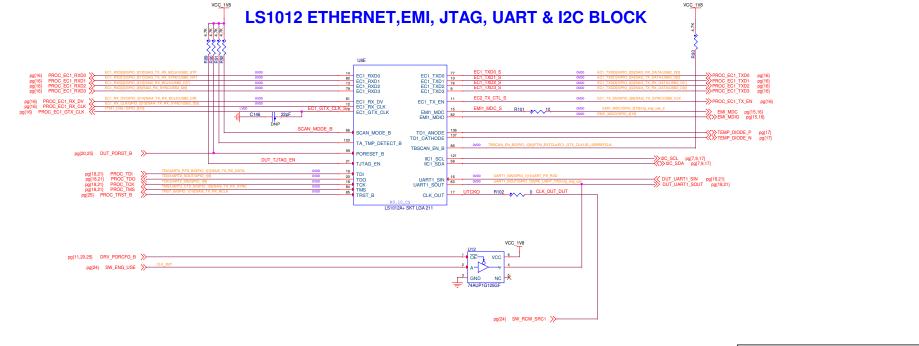
# LS1012 DDR3L CONTROLLER BLOCK



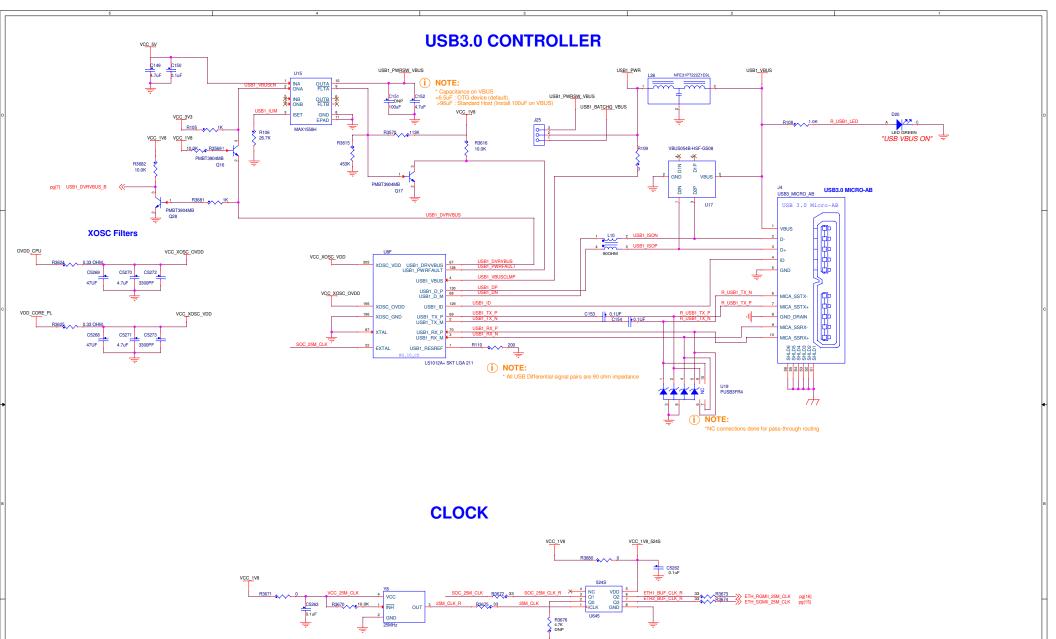






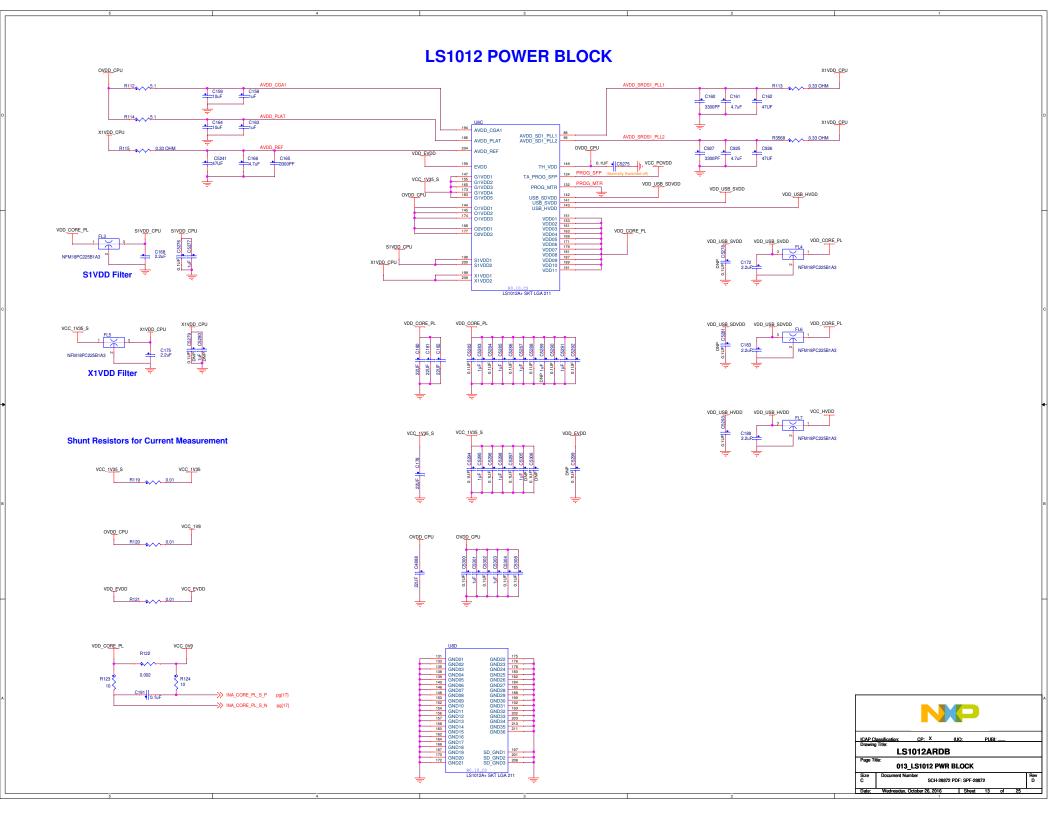






C5264

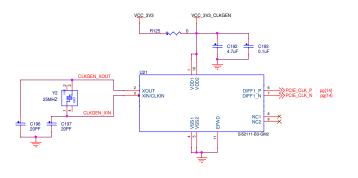




# SERDES MUXES SERDES LANEA MUX

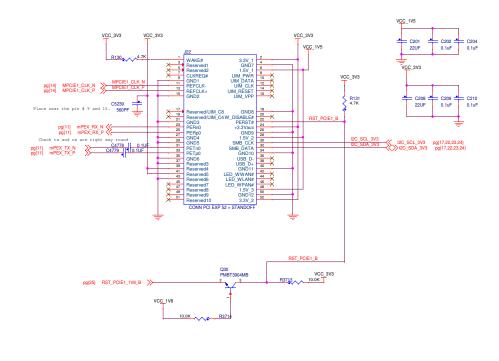
# VCC\_3V9 VCC\_3V9

# **PCIE HCSL CLOCK GENERATOR**

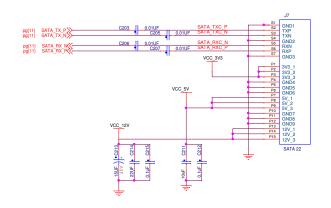


# Half mini-PClex1

#### MINI PCI EXPRESS1

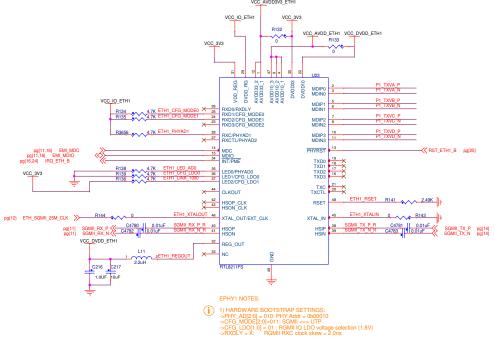


## **SATA3.0 INTERFACE**

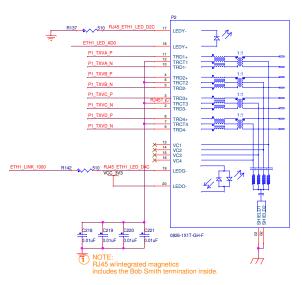


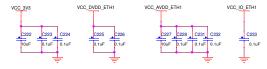


# ETHERNET SGMII PHY INTERFACE

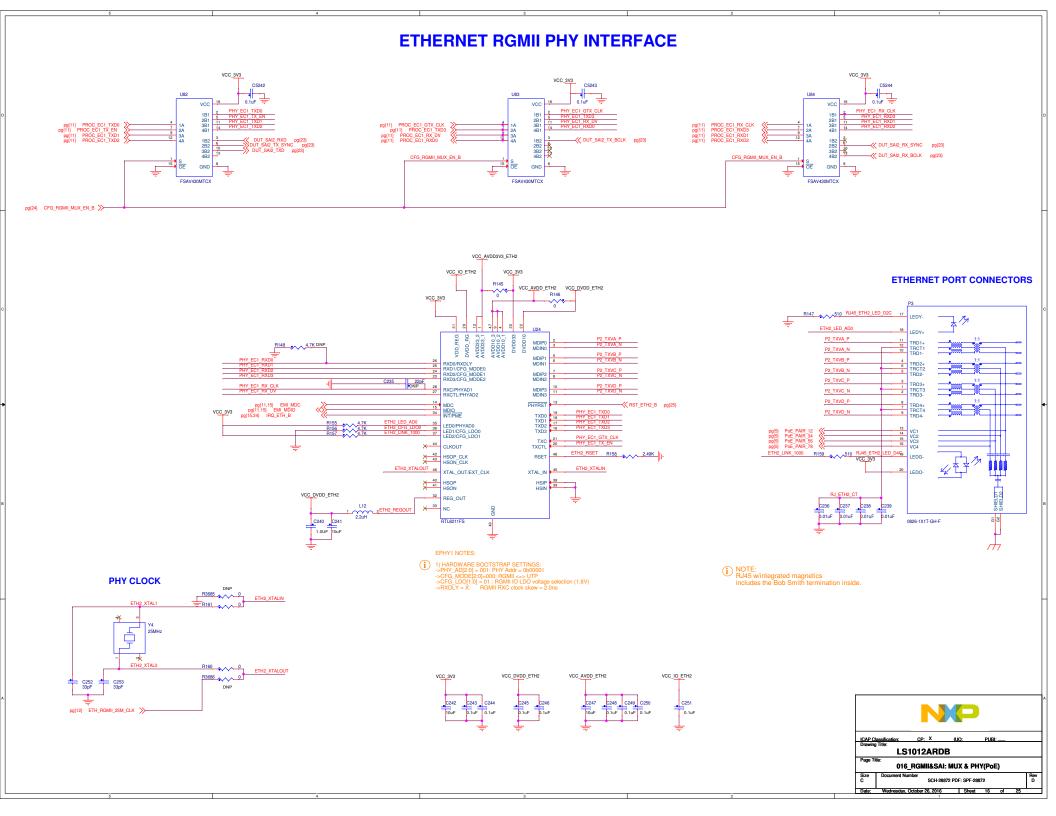


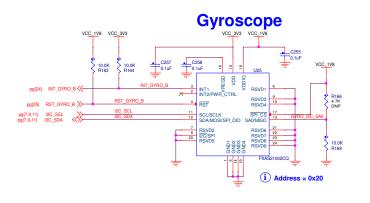
#### ETHERNET PORT CONNECTORS

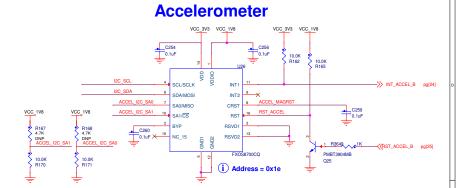




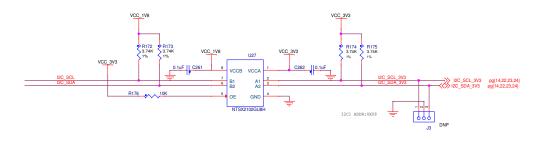
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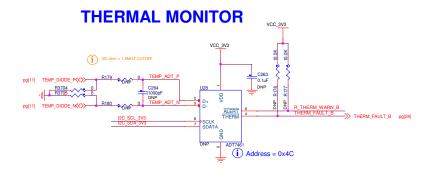




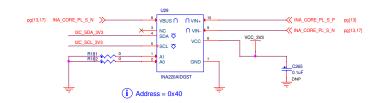


# I2C 1.8V <=> 3.3V



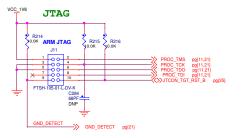


# CURRENT & POWER MONITOR

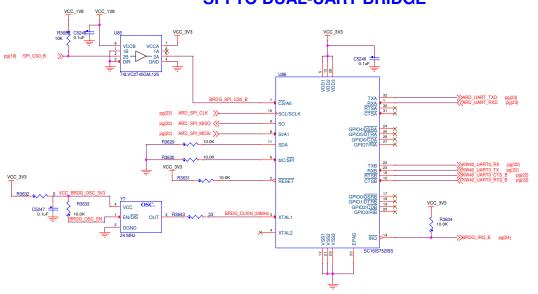




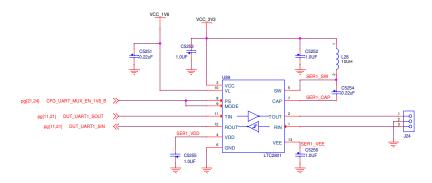
# **ARM JTAG CONNECTION**



# **SPI TO DUAL-UART BRIDGE**

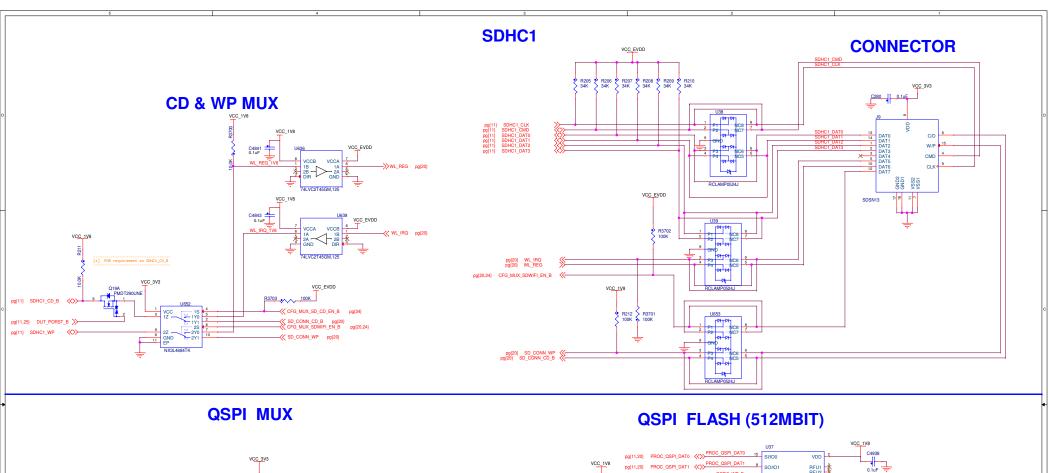


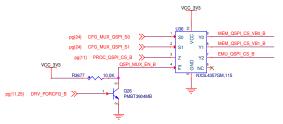
### **UART TRANSCEIVER**



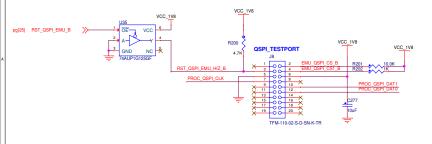


# eMMC on SDHC2 **SDHC2 MUX** CFG\_MUX\_SDHC2\_S[1:0] INTERFACE VCC\_1V8 C267 2.2uF C270 2.2uF pg[11] PROC\_SDHC2\_CMD <<>>> SPI\_MOSI >>SPI\_MOSI pg{23} eMMC\_VDDIM VDDIM CMD pg{11} PROC\_SDHC2\_DAT3 <<>> M6 CLK EN +1 MTEC4GACAAAM-1M WT PI3USB14-ALE " MMC\_DAT2 <<>>DUT\_GPIO\_1[27] pg{23} P221-882 pg{11} PROC\_SDHC2\_DAT2 <<>> ### AT NC A1 \*\*A1 NC A2 \*\*A0 NC A8 \*\*A0 NC A8 \*\*A10 NC A9 \*\*A11 NC A1 \*\*B1 NC B1 \* pg{11} PROC\_SDHC2\_DAT1 <<>> EN 1 PI3USB14-ALE o THE SECOND SECON pg(11) PROC\_SDHC2\_DAT0 <<>>-MTFC4GACAAAM-1M WT eMMC\_CLK DUT\_GPO\_1[29] pg(23) SPI\_CLK SPI\_CLK pg(23) pg(11) PROC\_SDHC2\_CLK >>-LS1012ARDB pg(24) CFG MUX SDHC2 S0 >> 019\_SHDC2: eMMC MEM & SD WiFi pg(24) CFG\_MUX\_SDHC2\_S1 >> SCH-28872 PDF: SPF-28872 Nednesday, October 26, 2016 Sheet 19





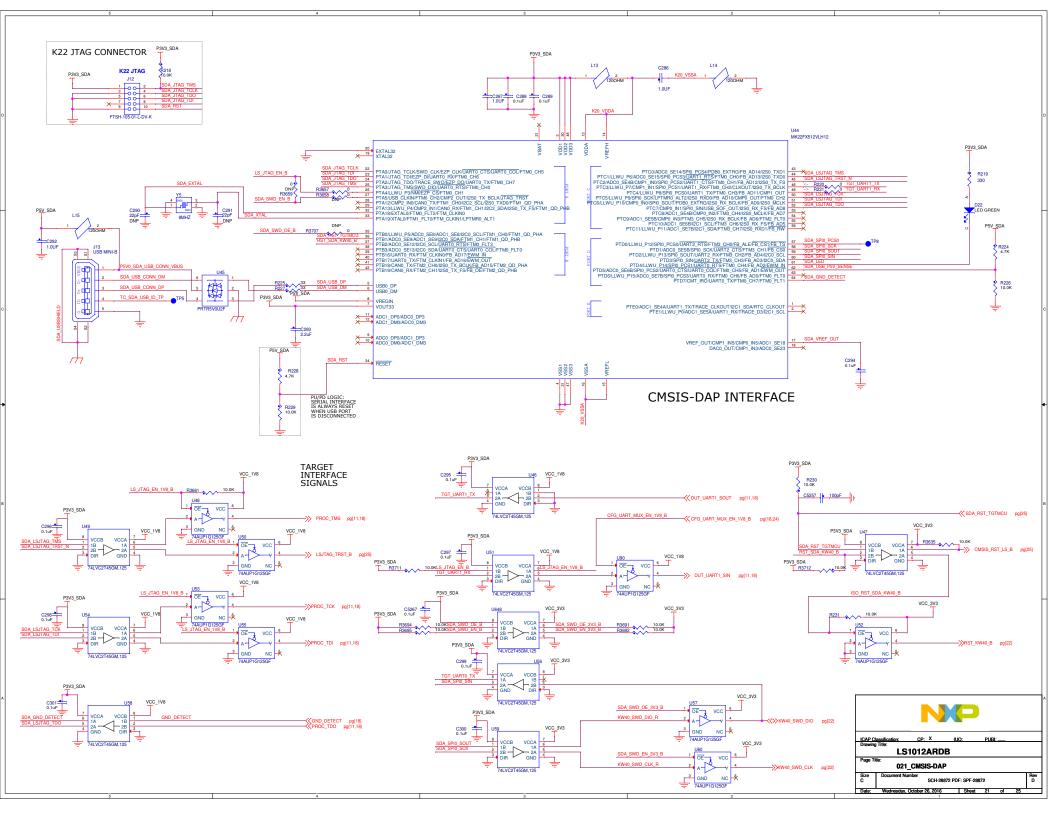
# **QSPI EMULATOR**

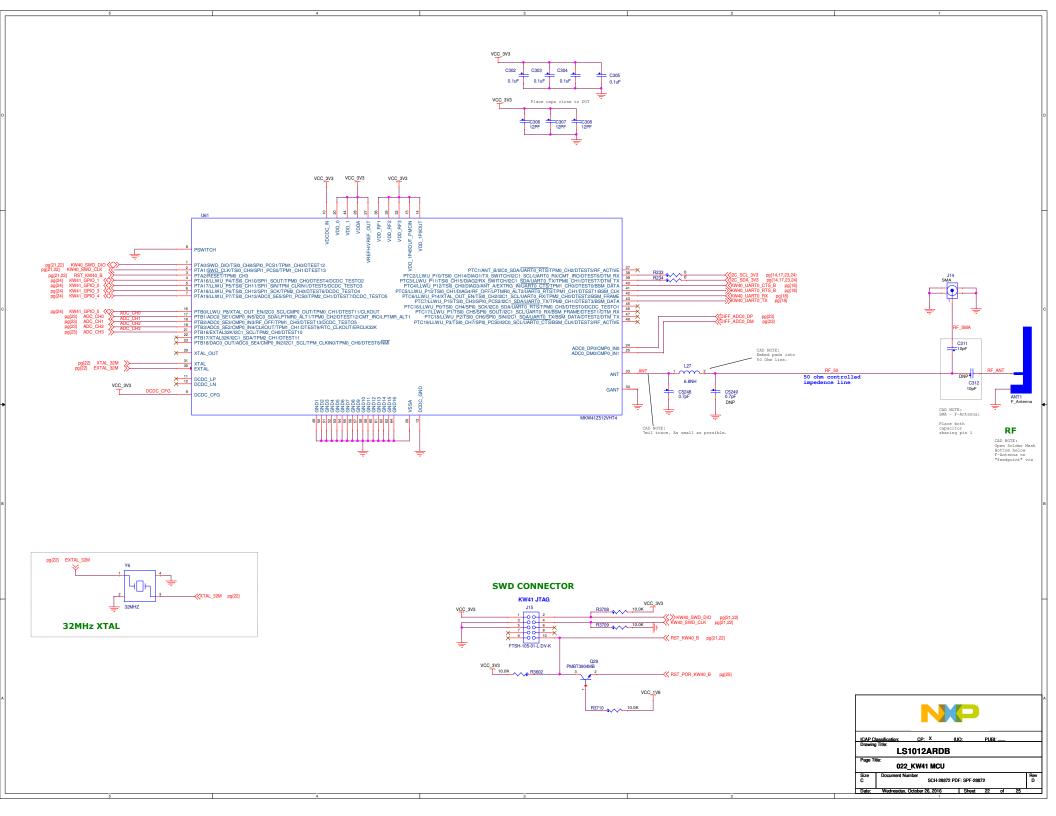


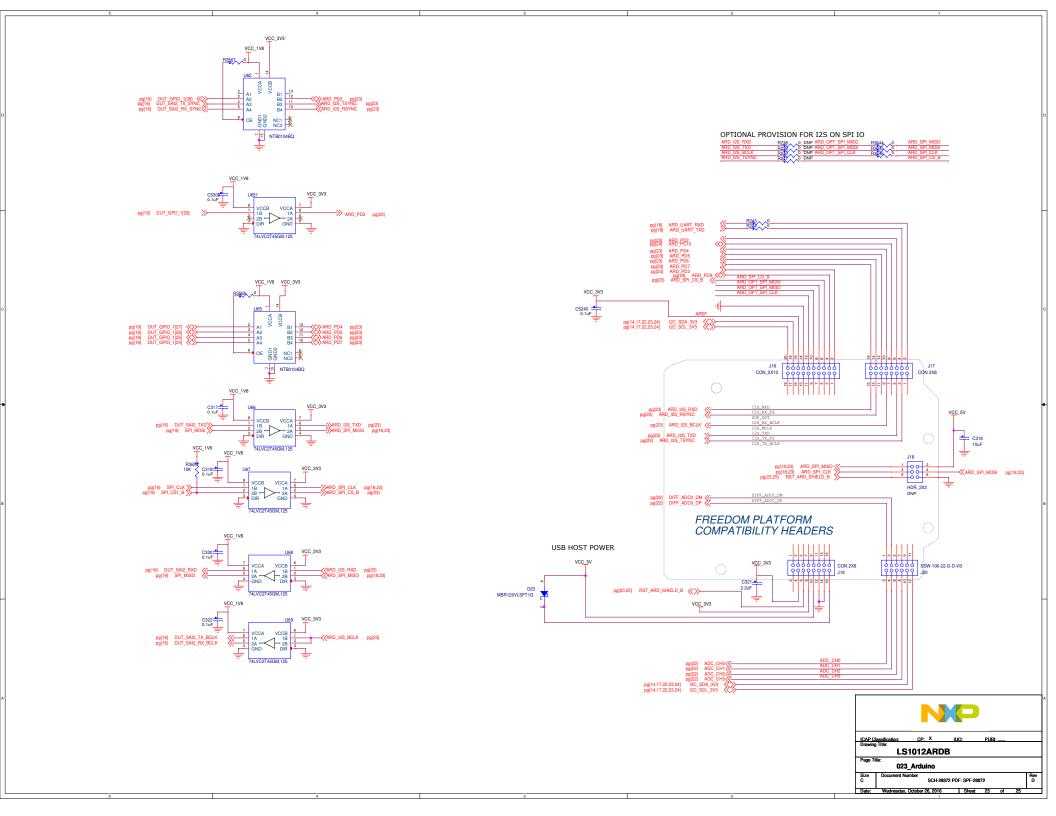


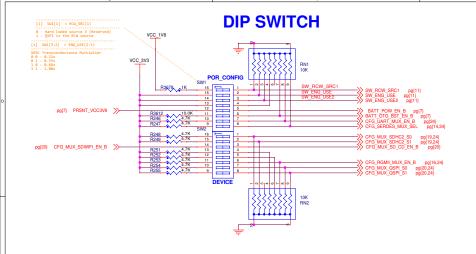




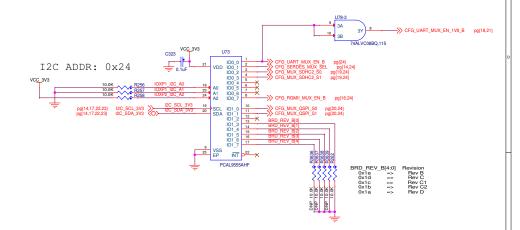




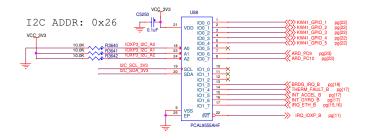




## **I2C IO-EXPANDER: MUX SEL**



## **12C IOEXPANDER: INTERRUPT AND GPIO**



# **I2C IO-EXPANDER: RESET**

